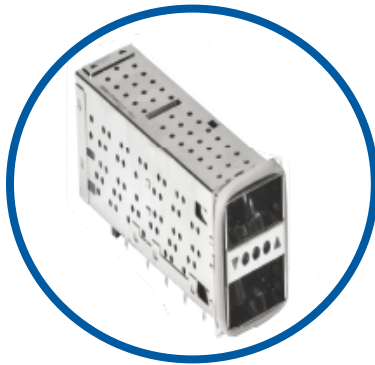
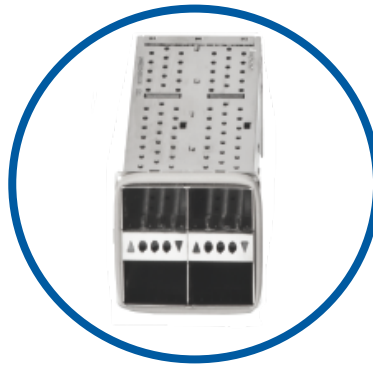


UltraPort™ QSFP+ Stacked

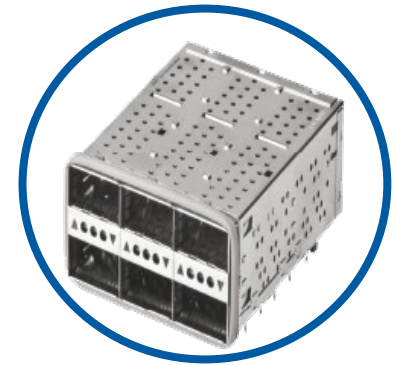
The UltraPort™ QSFP+ interconnect system is comprised of a 38-position, 0.8mm pitch connector built for use in high speed serial applications. Each port offers 4 channels to increase port density which contributes to more board real estate and immense cost savings. High speed serial interconnect applications include clusters, servers, and storage devices.



P-U95-Z105-XXX1-XX1



P-U95-Z205-XXX1-XX1



P-U95-Z305-XXX1-XX1

Specification Highlights

The UltraPort™ QSFP+ interconnect system is comprised of a 38-position, 0.8mm pitch connector built for use in high speed serial applications and supports 32 Gbps per channel. Each port offers 4 channels to increase port density.

General Characteristics

- RoHS Compliant
- Industry Standard Footprint
- Belly-to-belly Mount
- Combos are tray packed
- Dust cover for front face is available (bulk packed)

Connector Mechanical Characteristics

- Insertion force: 40 N maximum
- Withdrawal force: 30 N maximum
- Durability: 250 mating cycles

Connector Electrical Characteristics

- Maximum current: 0.5A per contact
- Maximum voltage: 30V per contact
- LLCR: 80 mΩ max
- Insulation Resistance: 1000 MΩ at 100V DC for 60 seconds
- DWV: 300V minimum DC for 60 seconds

Available Configurations (Rows x Ports/Row)

- 2x1,2x2,2x3,2x4

Material Requirements

Electrical connector chicklets:

- Contact area to have 15 μ" and 30 μ" gold option, over 50 μ" nickel on mating area
- Press fit termination to have 100-300 μ" nickel
- Molding body LCP

Housing: Glass-reinforced thermoplastic, UL 94 V-0 rated

Cage: Copper alloy, tin over nickel or nickel only plating

Temperature Rating

Temperature rise: Meets the requirement of 30° C ΔT

Operating and storage temperature: -40° to +85° C

Available Options

- Various EMI Shielding Options
- Heat Sinks
- Light Pipes
- Dust Covers
- Through and Behind the Bezel and Hybrid Cage Options

Supports Multiple Data Transfer Protocols

- Infiniband : 4x SDR/DDR/QDR/HDR
- 100 Gigabit Ethernet

UltraPort™ Stacked QSFP+

U95 - Z X 0 5 - X X X 1 - X X 1

U95	SERIES DESIGNATION (RoHS)	CONNECTOR FOOT PRINT 1-Standard	1
Z	STYLE Z-Standard	VENT HOLES AND EMI COVER 0 - With Large Vent Holes and EMI Cover 2 - With Small Vent Holes and EMI Cover 4 - With Rectangular Vent Holes and EMI Cover	X
X	NUMBER OF PORTS IN ROW 1 - 2x1 2 - 2x2 3 - 2x3 4 - 2x4 6 - 2x6	EMI GASKET 1 - Chomerics 1273 Conductive Elastomer 2 - Chomerics S6305 Conductive Elastomer 3 - Through the Bezel	X
0	HEAT SINK OPTION 0 - No Heat Sink or Clip Shipped	PACKAGING 1 - Tray Packaging	1
5	APPLICATION 5 - Press Fit Pins (2 mm Long)	LIGHT PIPES OPTION 6 - With Light Pipes (Triangular Outlet); Left Arrow Pointing Bottom Outlet and Right Arrow Pointing Top Port 7 - Without Light Pipes 8 - With Light Pipes; Left Arrow Pointing Top Port and Right Arrow Pointing Bottom Port	X
X	CAGE AND CONNECTOR CONTACT PLATING 4 - 0.76 µm Min. Gold over 1.27-3.81 µm of Nickel on Mating Area; 0.381-1.52 µm of Matte Tin Over 1.27-3.81 µm of Nickel on Press Fit Tail Area; Nickel Plating for Cage		
X	DUST COVER OPTION 0 - Without Dust Cover D - With Dust Cover		

